Isolators: Microstrip Substrate, Dual Magnet
5.6-6.6GHz, 0.3 Watts

5.1+0/-0.02 (0.200") Dia. Max 5.6-6.6GHz.

<table>
<thead>
<tr>
<th>I</th>
<th>C</th>
<th>RAD/C:- (GHz)</th>
<th>W mm</th>
<th>L mm</th>
<th>N mm</th>
<th>X mm</th>
<th>HS mm</th>
<th>S mm</th>
<th>Hb mm</th>
<th>l loss dB</th>
<th>Iso dB (typical)</th>
<th>RL dB</th>
<th>Pwr W Fwd</th>
<th>Pwr W Rev</th>
</tr>
</thead>
<tbody>
<tr>
<td>5.6-6.6</td>
<td>✓</td>
<td>✓</td>
<td>+0/0.12 (-0.005)</td>
<td>+0/0.15 (-0.006)</td>
<td>±0.05 (±0.002)</td>
<td>±1.5 (±0.06)</td>
<td>+0.5/0 (-0.02)</td>
<td>±0.03 (±0.001)</td>
<td>+0.2/0 (+0.008)</td>
<td>✓</td>
<td>✓</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Cust</td>
<td>12 (0.472)</td>
<td>15 (0.591)</td>
<td>2.54 (0.098)</td>
<td>5 (0.197)</td>
<td>3.5 (0.098)</td>
<td>1.0 (0.039)</td>
<td>2.0 (0.079)</td>
<td>0.5</td>
<td>18 (20)</td>
<td>18</td>
<td>2</td>
<td>0.3</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Survives non operating 205 °C for up to 3 min. to withstand reflow soldering with low temperature solder
Strontium magnet.

Machine surfaces
Flatness 0.025mm, (0.001/ inch)
Bend radius 0.8mm, (0.031” or 1/32”)

The thin film Microstrip lines are suitable for soldering or thermo-compression gap welding.
2 μm thin film Gold on 4μm Copper,

Specifications over full operating temperature (-40 to +85 °C)

Tolerance Table Metric (inch)
(unless otherwise stated):
Hole diameter +/- 0.1mm, (+/- 0.004")
Dimensions (w*l*h) +/- 0.3 mm, (+/- 0.015")
Dimensions (Microstrip pad, Stripline Tab,
+/- 0.1mm, (+/- 0.04")
Dimensions (hole position)
+/- 0.1mm, (+/- 0.04")

RADI-5.6-6.6-MSSDM-0.3WR-b
I=ISOLATOR

Their spec is 0.275”dia

Direction of RF:
R Default ▶
L ◀

Order Examples: RADI-5.6-6.6-MSSDM-0.3WR-b

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Strontium magnet,